

AMENDMENTS TO THE CLAIMS

1. (Currently Amended) A method comprising:
placing a substrate with a ferroelectric polymer layer formed thereon in a chamber; and
sputtering a metal layer ~~at a reduced flux~~ on the ferroelectric polymer layer in the presence of a flux reducer.
2. (Currently Amended) The method of Claim 1, wherein ~~sputtering the flux reducer~~
comprises ~~sputtering in the presence of~~ a collimator.
3. (Currently Amended) The method of Claim 2, wherein sputtering ~~may be performed~~ comprises sputtering at a pressure less than approximately 10 milliTorr.
4. (Currently Amended) The method of Claim 3, wherein sputtering ~~may be performed~~ comprises sputtering at a pressure equal to or less than approximately 2.5 milliTorr.
5. (Original) The method of Claim 1, wherein sputtering comprises:
forming a metal layer of at least one of TiN, TaN, TiNSi, and TaNSi.
6. (Original) The method of Claim 1, wherein sputtering comprises:
sputtering with an ion gun.
7. (Original) A method comprising:
placing a substrate with a ferroelectric polymer layer formed thereon in a chamber; and
forming an intermetallic layer between a metal layer and the ferroelectric polymer layer.
8. (Original) The method of Claim 7, wherein forming comprises:
sputtering with an ion gun.
9. (Original) The method of Claim 7, wherein forming comprises:
forming a layer of at least one of TiN, TaN, TiNSi, and TaNSi.

10. (Original) The method of Claim 7, further comprising:
amorphizing the intermetallic layer.
11. (Original) The method of Claim 10, wherein amorphizing comprises:
implanting ions within the intermetallic layer.
12. (Original) The method of Claim 11, wherein implanting comprises:
implanting at least one of Si ions, Ge ions, and any of the inert gas ions in the
intermetallic layer.
13. (Original) The method of Claim 10, wherein amorphizing comprises:
forming the intermetallic layer with a technique that renders the intermetallic layer
amorphous.
14. (Original) The method of Claim 13, wherein forming comprises:
forming the intermetallic layer with a chemical vapor deposition process.
- 15-24 (Canceled)